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List of Patents and Publication For Applicant's Information
Disclosure Statement

TTY. DKT. NO. 5589-05001

APPLICANT: Xu et al.

SERIAL NO. 10/699,352

GROUP: 2858 2829

E	Disclos	ure Statement	FILING DA	TE: October 31, 2003			2027
(USE	severa	I sheets if necessary)	<u> </u>	DOCUMENTS		· · · · · · · · · · · · · · · · · · ·	
EXAM. INITIALS	REF. DES.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
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EXAM. INITIALS	REF. DES.	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO
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EXAMINER: John Hyt

DATE CONSIDERED: 3/7/05

EXAMINER: Initial if citation to hsidered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the patent owner.



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention

METHODS AND SYSTEMS FOR DETERMINING AN ELECTRICAL PROPERTY OF AN INSULATING FILM

Application Number:

10/699352

Confirmation Number:

Attorney Docket Number: 5589-05001

2525

First Named Applicant:

Zhiwei Xu

Search string:

(5485091 or 6097196 or 6202029 or 4599558

or 5594247 or 5644223 or 4812756 or 5650731 or 5767693 or 5661408 or 5742658 or 5852232 or 5866806 or 5948972 or 5955661 or 6011404 or 6191605 or 6267005 or 5773989 or 6569691 or 3495269 or 3496352 or 4734721 or 5834941

or 6060709 or 6072320 or 6091257 or 6104206

or 6121783 or 6201999 or 6224638 or

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gH 1	20020090746	2002-07-11	Xu et al.			

Signature

Date Date
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